

DERWENT-ACC-NO: 1998-278306
DERWENT-WEEK: 199825
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TITLE: Semiconductor substrate for electronic component mounting - includes metal plating with multiple step portions of varying film thickness, which is coated over land and conductor circuit

PATENT-ASSIGNEE: IBIDEN CO LTD[IBIG]

PRIORITY-DATA: 1988JP-0197755 (August 8, 1988) , 1997JP-0242112 (August 8, 1988)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 10093215 A	April 10, 1998	N/A	006	H05K 001/11

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP10093215A	Div ex	1988JP-0197755	August 8, 1988
JP10093215A	N/A	1997JP-0242112	August 8, 1988

INT-CL_(IPC): H05K001/11

RELATED-ACC-NO: 1990-095214

ABSTRACTED-PUB-NO: JP10093215A

BASIC-ABSTRACT: The substrate (10) includes several conductor circuits (3) which are extended towards an insulated area (1) formed at the periphery of an electronic component mounting portion (2). A through hole (4) is formed on one end of the conductor circuit. A circuit pattern (9) is formed between a land (6) of the through hole and the conductor circuit. The circuit pattern is formed such that it extends towards the conductor circuit from a side portion (69) of the land.

The width of an installation portion (91) of the land is greater than that of the circuit pattern. A tapered portion (92) is formed in the land, which has a width which is gradually reduced from the installation portion towards the conductor circuit. A metal plating with multiple step portions of varying film thickness, is coated over the land and the conductor circuit.

ADVANTAGE - Maintains conducting reliability between conductor circuit and land of through-hole.

CHOSEN-DRAWING: Dwg.1/23

TITLE-TERMS:

SEMICONDUCTOR SUBSTRATE ELECTRONIC COMPONENT MOUNT METAL PLATE
MULTIPLE STEP
PORTION VARY FILM THICK COATING LAND CONDUCTOR CIRCUIT

DERWENT-CLASS: V04

EPI-CODES: V04-Q01;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N1998-219214